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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	46
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51117adfk-3a

Table 1.2 Comparison of Functions for Different Packages

Module/Functions		RX111 Group			
		64 Pins	48 Pins	40 Pins	36 Pins
Interrupts	External interrupts	NMI, IRQ0 to IRQ7			
DMA	Data transfer controller	Supported			
Timers	Multi-function timer pulse unit 2	6 channels (MTU0 to MTU5)			
	Port output enable 2	POE0# to POE3#, POE8#		POE0#, POE2#, POE3#, POE8#	
	Compare match timer	2 channels × 1 unit			
	Realtime clock	Supported		Not supported	
	Independent watchdog timer	Supported			
Communication functions	Serial communications interfaces [simple I^2C, simple SPI]	2 channels (SCI1, SCI5)			
	Serial communications interface [simple I^2C, simple SPI]	1 channel (SCI12)			
	I^2C bus interface	1 channel			
	Serial peripheral interface	1 channel	1 channel (SSLA1 and SSLA3 are not supported)		1 channel (SSLA1 to SSLA3 are not supported)
	USB 2.0 host/function module (USBc)	1 channel (Host/Function/ OTG)	1 channel (Host/Function)		
12-bit A/D converter (including high-precision channels)		14 channels (6 channels)	10 channels (4 channels)	8 channels (3 channels)	7 channels (2 channels)
D/A converter		2 channels	Not supported		
Temperature sensor		Supported			
CRC calculator		Supported			
Event link controller		Supported			
Packages		64-pin LFQFP 64-pin LQFP 64-pin WFLGA	48-pin LFQFP 48-pin HWQFN	40-pin HWQFN	36-pin WFLGA

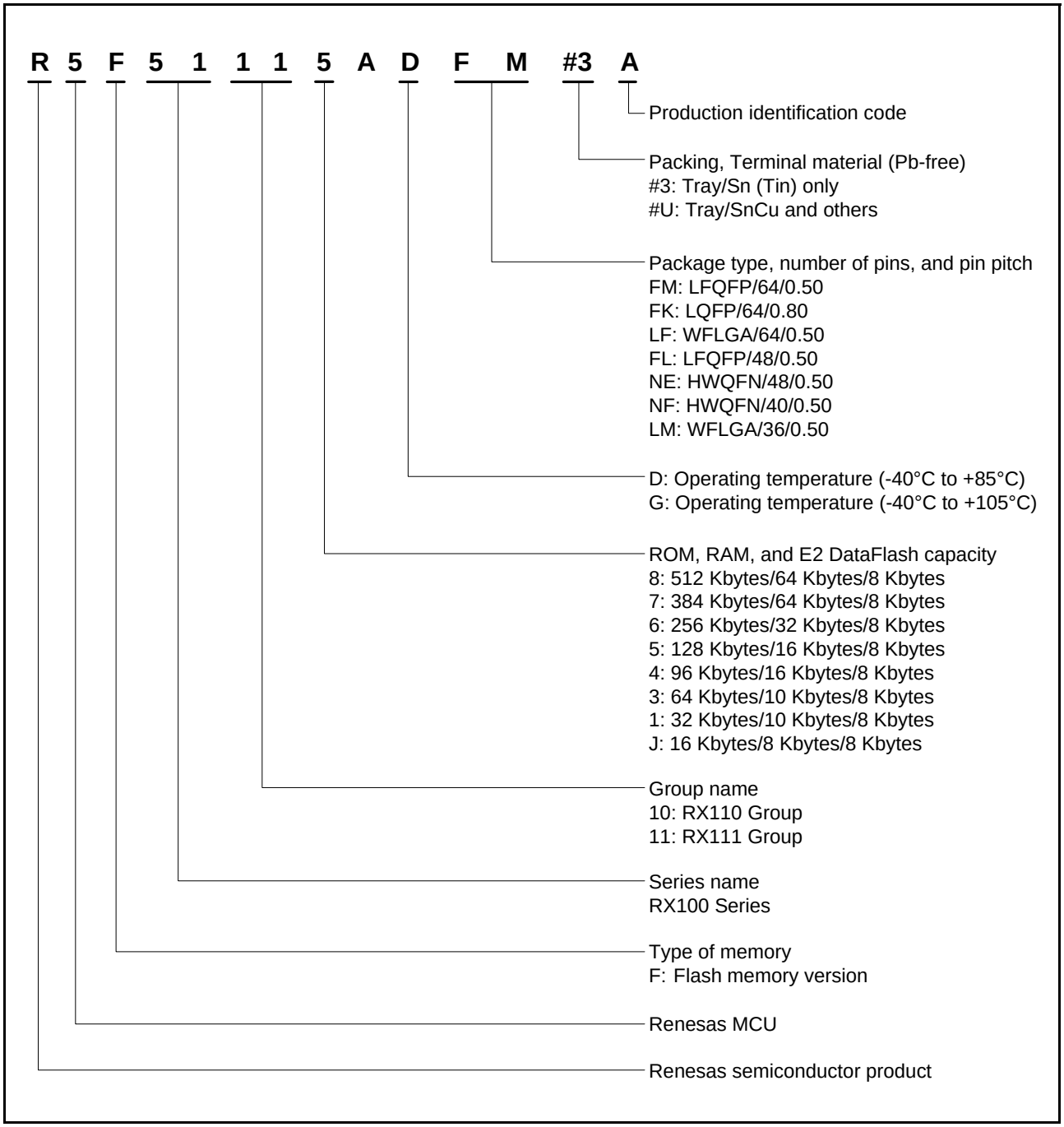
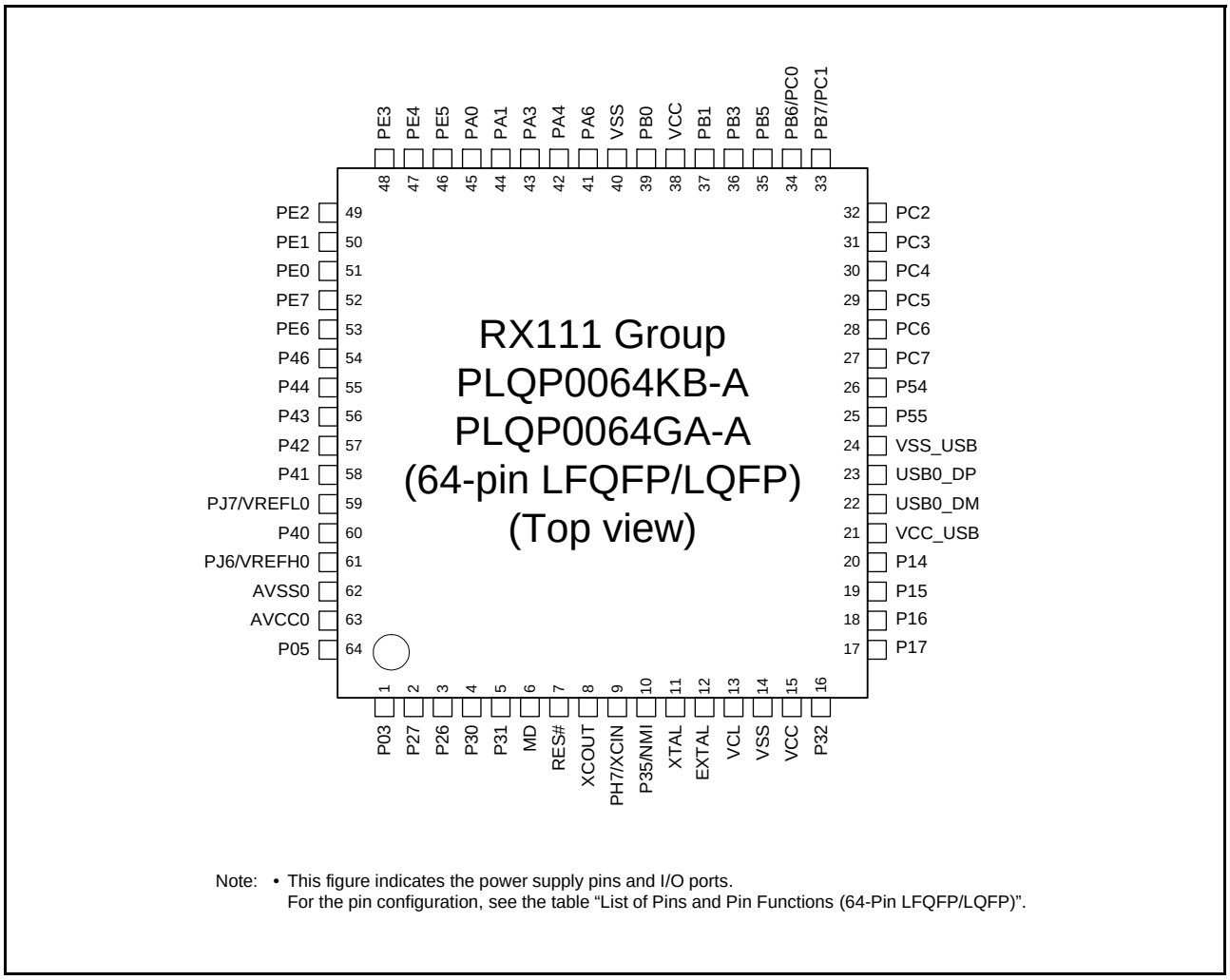


Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type

1.5 Pin Assignments

Figure 1.3 to Figure 1.7 show the pin assignments. Table 1.5 to Table 1.9 show the lists of pins and pin functions.



Note: • This figure indicates the power supply pins and I/O ports.
For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin LFQFP/LQFP)”.

Figure 1.3 Pin Assignments of the 64-Pin LFQFP/LQFP

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC)	Communication (SCIe, SCIf, RSPI, RIIC, USB)	Others
39		PE0	MTIOC2A/POE3#	SCK12	IRQ0/AN008
40		PE7			IRQ7/AN015
41		P46*2			AN006
42		P42*2			AN002
43		P41*2			AN001
44	VREFL0	PJ7*2			
45		P40*2			AN000
46	VREFH0	PJ6*2			
47	AVSS0				
48	AVCC0				

Note 1. Not 5 V tolerant.
Note 2. The power source of the I/O buffer for these pins is AVCC0.

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to I/O registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

While writing to an I/O register, the CPU starts executing subsequent instructions before the I/O register write access is completed. This may cause the subsequent instructions to be executed before the write value is reflected in the operation. The examples below show how subsequent instructions must be executed after a write access to an I/O register is completed.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) set to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value in the I/O register and write it to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

Example of instructions

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

Table 4.1 List of I/O Registers (Address Order) (5/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 7343h	ICU	Interrupt Source Priority Register 067	IPR067	8	8	2 ICLK
0008 7344h	ICU	Interrupt Source Priority Register 068	IPR068	8	8	2 ICLK
0008 7345h	ICU	Interrupt Source Priority Register 069	IPR069	8	8	2 ICLK
0008 7346h	ICU	Interrupt Source Priority Register 070	IPR070	8	8	2 ICLK
0008 7347h	ICU	Interrupt Source Priority Register 071	IPR071	8	8	2 ICLK
0008 7358h	ICU	Interrupt Source Priority Register 088	IPR088	8	8	2 ICLK
0008 7359h	ICU	Interrupt Source Priority Register 089	IPR089	8	8	2 ICLK
0008 735Ah	ICU	Interrupt Source Priority Register 090	IPR090	8	8	2 ICLK
0008 735Ch	ICU	Interrupt Source Priority Register 092	IPR092	8	8	2 ICLK
0008 735Dh	ICU	Interrupt Source Priority Register 093	IPR093	8	8	2 ICLK
0008 7366h	ICU	Interrupt Source Priority Register 102	IPR102	8	8	2 ICLK
0008 7367h	ICU	Interrupt Source Priority Register 103	IPR103	8	8	2 ICLK
0008 736Ah	ICU	Interrupt Source Priority Register 106	IPR106	8	8	2 ICLK
0008 7372h	ICU	Interrupt Source Priority Register 114	IPR114	8	8	2 ICLK
0008 7376h	ICU	Interrupt Source Priority Register 118	IPR118	8	8	2 ICLK
0008 7379h	ICU	Interrupt Source Priority Register 121	IPR121	8	8	2 ICLK
0008 737Bh	ICU	Interrupt Source Priority Register 123	IPR123	8	8	2 ICLK
0008 737Dh	ICU	Interrupt Source Priority Register 125	IPR125	8	8	2 ICLK
0008 737Fh	ICU	Interrupt Source Priority Register 127	IPR127	8	8	2 ICLK
0008 7381h	ICU	Interrupt Source Priority Register 129	IPR129	8	8	2 ICLK
0008 7385h	ICU	Interrupt Source Priority Register 133	IPR133	8	8	2 ICLK
0008 7386h	ICU	Interrupt Source Priority Register 134	IPR134	8	8	2 ICLK
0008 738Ah	ICU	Interrupt Source Priority Register 138	IPR138	8	8	2 ICLK
0008 738Bh	ICU	Interrupt Source Priority Register 139	IPR139	8	8	2 ICLK
0008 73AAh	ICU	Interrupt Source Priority Register 170	IPR170	8	8	2 ICLK
0008 73ABh	ICU	Interrupt Source Priority Register 171	IPR171	8	8	2 ICLK
0008 73DAh	ICU	Interrupt Source Priority Register 218	IPR218	8	8	2 ICLK
0008 73DEh	ICU	Interrupt Source Priority Register 222	IPR222	8	8	2 ICLK
0008 73EEh	ICU	Interrupt Source Priority Register 238	IPR238	8	8	2 ICLK
0008 73F2h	ICU	Interrupt Source Priority Register 242	IPR242	8	8	2 ICLK
0008 73F3h	ICU	Interrupt Source Priority Register 243	IPR243	8	8	2 ICLK
0008 73F4h	ICU	Interrupt Source Priority Register 244	IPR244	8	8	2 ICLK
0008 73F5h	ICU	Interrupt Source Priority Register 245	IPR245	8	8	2 ICLK
0008 73F6h	ICU	Interrupt Source Priority Register 246	IPR246	8	8	2 ICLK
0008 73F7h	ICU	Interrupt Source Priority Register 247	IPR247	8	8	2 ICLK
0008 73F8h	ICU	Interrupt Source Priority Register 248	IPR248	8	8	2 ICLK
0008 73F9h	ICU	Interrupt Source Priority Register 249	IPR249	8	8	2 ICLK
0008 7500h	ICU	IRQ Control Register 0	IRQCR0	8	8	2 ICLK
0008 7501h	ICU	IRQ Control Register 1	IRQCR1	8	8	2 ICLK
0008 7502h	ICU	IRQ Control Register 2	IRQCR2	8	8	2 ICLK
0008 7503h	ICU	IRQ Control Register 3	IRQCR3	8	8	2 ICLK
0008 7504h	ICU	IRQ Control Register 4	IRQCR4	8	8	2 ICLK
0008 7505h	ICU	IRQ Control Register 5	IRQCR5	8	8	2 ICLK
0008 7506h	ICU	IRQ Control Register 6	IRQCR6	8	8	2 ICLK
0008 7507h	ICU	IRQ Control Register 7	IRQCR7	8	8	2 ICLK
0008 7510h	ICU	IRQ Pin Digital Filter Enable Register 0	IRQFLTE0	8	8	2 ICLK
0008 7514h	ICU	IRQ Pin Digital Filter Setting Register 0	IRQFLTC0	16	16	2 ICLK
0008 7580h	ICU	Non-Maskable Interrupt Status Register	NMISR	8	8	2 ICLK
0008 7581h	ICU	Non-Maskable Interrupt Enable Register	NMIER	8	8	2 ICLK
0008 7582h	ICU	Non-Maskable Interrupt Status Clear Register	NMICLR	8	8	2 ICLK
0008 7583h	ICU	NMI Pin Interrupt Control Register	NMICR	8	8	2 ICLK
0008 7590h	ICU	NMI Pin Digital Filter Enable Register	NMIFLTE	8	8	2 ICLK

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	VCC × 0.7	—	5.8	V	
	Ports P16, P17, port PA6, port PB0 (5 V tolerant)		VCC × 0.8	—	5.8		
	Ports P03, P05, ports P14,P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PE0 to PE7, port PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (except for SMBus)	V_{IL}	–0.3	—	VCC × 0.3		
	Other than RIIC input pin		–0.3	—	VCC × 0.2		
	RIIC input pin (except for SMBus)	ΔV_T	VCC × 0.05	—	—		
	Other than RIIC input pin		VCC × 0.1	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	RIIC input pin (SMBus)		2.1	—	VCC + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		
	RIIC input pin (SMBus)		–0.3	—	0.8		

Table 5.4 DC Characteristics (2)

Conditions: 1.8 V ≤ VCC = VCC_USB < 2.7 V, 1.8 V ≤ AVSS0 < 2.7 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P16, P17, port PA6, port PB0 (5 V tolerant)	V_{IH}	VCC × 0.8	—	5.8	V	
	Ports P03, P05, ports P14,P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PE0 to PE7, port PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	All pins		–0.3	—	VCC × 0.2		
	All pins	ΔV_T	VCC × 0.01	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		

Table 5.5 DC Characteristics (3)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35, port PH7	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V, VCC
Three-state leakage current (off-state)	Ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V, 5.8 V
	Pins other than above		—	—	1.0		V_{in} = 0 V, VCC
Input capacitance	All input pins (except for port P16, port P35, USB0_DM, USB0_DP)	C_{in}	—	—	15	pF	V_{in} = 0 mV, Frequency: 1 MHz, T_a = 25°C
	Port P16, port P35, USB0_DM, USB0_DP		—	—	30		

Table 5.6 DC Characteristics (4)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for port P35, port PH7)	R_U	10	20	100	kΩ	V_{in} = 0 V

[256-Kbyte or more flash memory]

Table 5.8 DC Characteristics (6) (1/2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32 MHz	I_{CC}	3.6	—	mA	
				ICLK = 16 MHz		2.4	—		
				ICLK = 8 MHz		1.8	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		13.4	—		
				ICLK = 16 MHz		7.5	—		
				ICLK = 8 MHz		4.5	—		
			All peripheral operation: Max.*3	ICLK = 32 MHz		—	27		
		Sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.9	—		
				ICLK = 16 MHz		1.5	—		
				ICLK = 8 MHz		1.3	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		7.6	—		
				ICLK = 16 MHz		4.4	—		
				ICLK = 8 MHz		2.8	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.1	—		
				ICLK = 16 MHz		1.0	—		
				ICLK = 8 MHz		0.9	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		5.8	—		
				ICLK = 16 MHz		3.4	—		
				ICLK = 8 MHz		2.1	—		
		Increase during flash rewrite*5				2.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*6	ICLK = 12 MHz	I_{CC}	2.1	—	mA	
				ICLK = 8 MHz		1.4	—		
				ICLK = 1 MHz		0.8	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		5.9	—		
				ICLK = 8 MHz		4.2	—		
				ICLK = 1 MHz		1.3	—		
			All peripheral operation: Max.*7	ICLK = 12 MHz		—	12.2		
		Sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.4	—		
				ICLK = 8 MHz		0.9	—		
				ICLK = 1 MHz		0.7	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		3.6	—		
				ICLK = 8 MHz		2.5	—		
				ICLK = 1 MHz		1.1	—		
		Deep sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.1	—		
				ICLK = 8 MHz		0.6	—		
				ICLK = 1 MHz		0.6	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		2.9	—		
				ICLK = 8 MHz		2.0	—		
				ICLK = 1 MHz		0.9	—		
		Increase during flash rewrite*5				2.5	—		

Table 5.12 DC Characteristics (10)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.*7	Max.	Unit	Test Conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	—	0.7	1.2	mA	
	Waiting for A/D (all units)		—	—	0.3	µA	
	During D/A conversion (per channel)*5		—	—	1.5	mA	
Reference power supply current	During A/D conversion (at high-speed conversion)	I_{REFH0}	—	25	52	µA	
	Waiting for A/D conversion (all units)		—	—	60	nA	
Temperature sensor*6		I_{TEMP}	—	75	—	µA	
LDV1, 2	Per channel	I_{LVD}	—	0.15	—	µA	
USB operating current	During USB communication operation under the following settings and conditions • Host controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect peripheral devices via a 1-meter USB cable from the USB port.	I_{USBH}*2	—	4.3 (VCC) 0.9 (VCC_USB) *4	—	mA	
	During USB communication operation under the following settings and conditions • Function controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect the host device via a 1-meter USB cable from the USB port.	I_{USBF}*2	—	3.6 (VCC) 1.1 (VCC_USB) *4	—	mA	
	During suspended state under the following setting and conditions • Function controller operation is set to full-speed mode (pull up the USB0_DP pin) • Software standby mode • Connect the host device via a 1-meter USB cable from the USB port.	I_{SUSP}*3	—	0.35 (VCC) 170 (VCC_USB) *4	—	µA	

Note 1. The reference power supply current is included in the power supply current value for D/A conversion.
Note 2. Current consumed only by the USB module.
Note 3. Includes the current supplied from the pull-up resistor of the USB0_DP pin to the pull-down resistor of the host device, in addition to the current consumed by this MCU during the suspended state.
Note 4. When VCC = VCC_USB = 3.3 V.
Note 5. The value of the current flowing to VCC.
Note 6. Current consumed by the power supply (VCC).
Note 7. When VCC = AVCC0 = VCC_USB = 3.3 V.

Table 5.13 DC Characteristics (11)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

Table 5.19 Output Voltage (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for RIIC, ports P40 to P44, P46, ports PJ6, PJ7)		V_{OL}	—	0.6	V	I_{OL} = 3.0 mA
				—	0.4		I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			—	0.4		I_{OL} = 0.4 mA
	RIIC pins	Standard mode		—	0.4		I_{OL} = 3.0 mA
		Fast mode		—	0.6		I_{OL} = 6.0 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)		V_{OH}	VCC – 0.5	—	V	I_{OH} = –2.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			AVCC0 – 0.5	—		I_{OH} = –0.1 mA

Table 5.20 Output Voltage (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 2.7 V, 1.8 V ≤ AVSS0 ≤ 2.7 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OL}	—	0.6	V	I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		—	0.4		I_{OL} = 0.4 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OH}	VCC – 0.5	—	V	I_{OH} = –1.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 – 0.5	—		I_{OH} = –0.1 mA

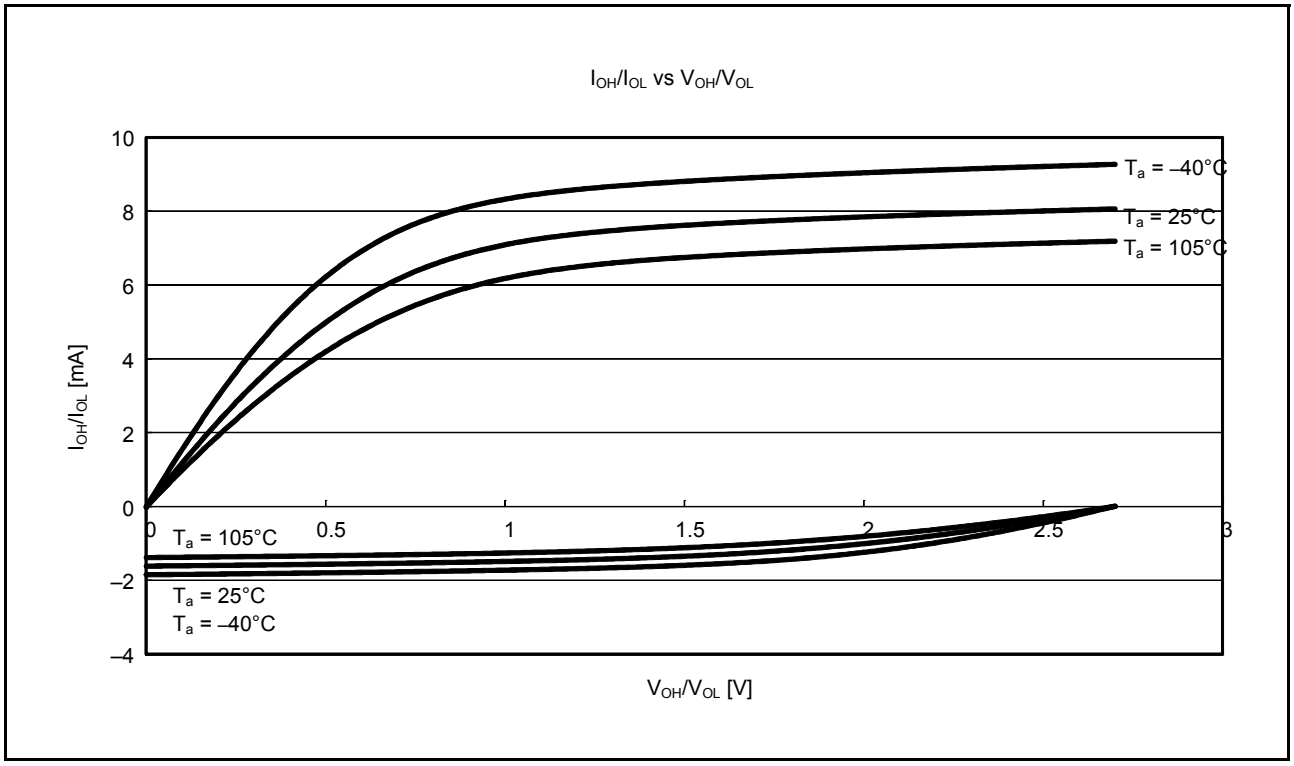


Figure 5.21 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 2.7 V (Reference Data)

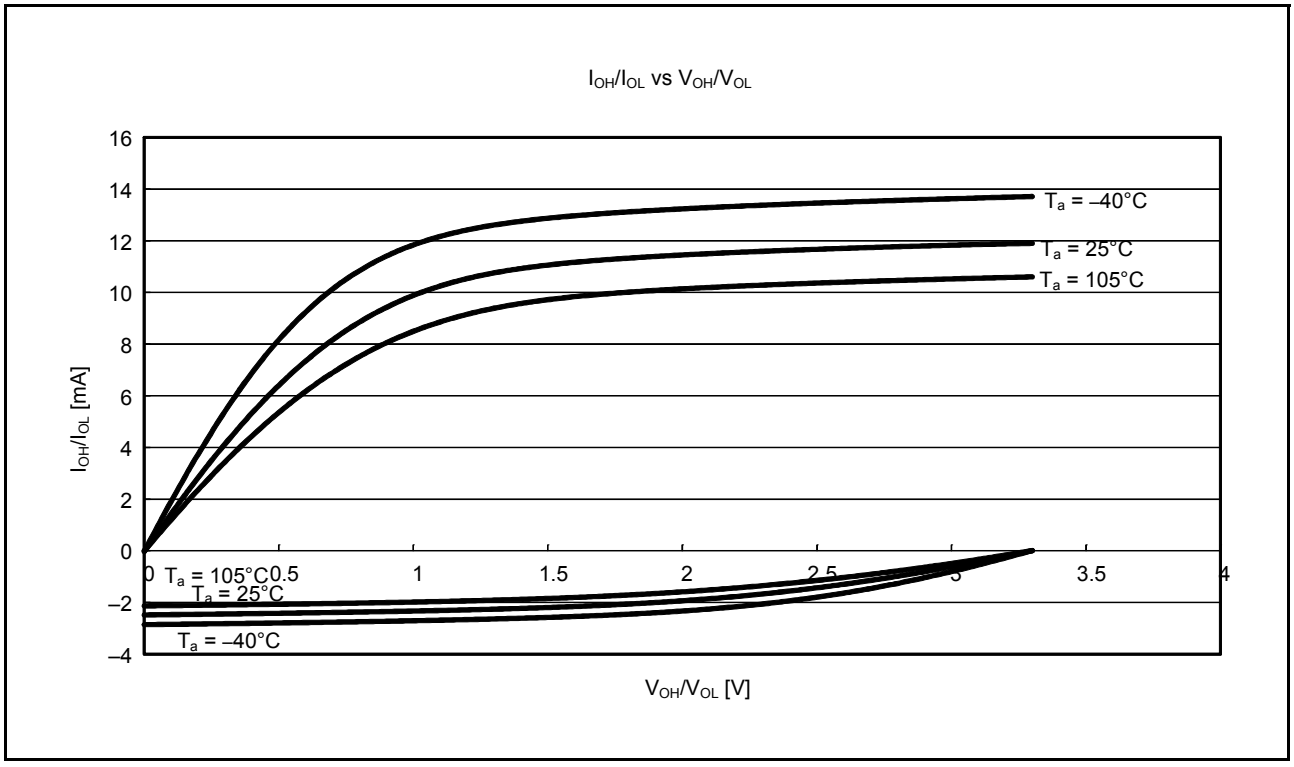


Figure 5.22 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports PJ6, PJ7 at VCC = 3.3 V (Reference Data)

Table 5.34 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V,
T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.46
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.47, Figure 5.49
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.51, Figure 5.52
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

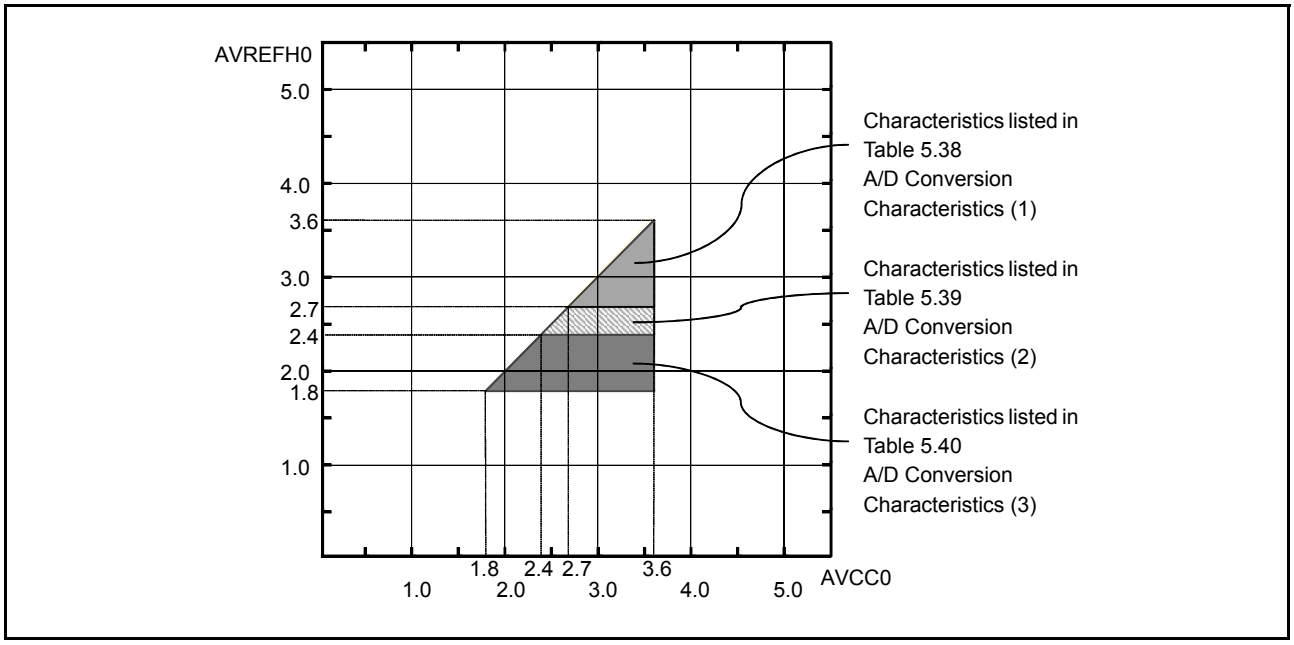


Figure 5.56 AVCC0 to AVREFH0 Voltage Range

5.8 Power-On Reset Circuit and Voltage Detection Circuit Characteristics

Table 5.45 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	1.35	1.50	1.65	V	Figure 5.58, Figure 5.59
	Voltage detection circuit (LVD1)*1	V_{det1_4}	3.00	3.10	3.20	V	Figure 5.60 At falling edge VCC
		V_{det1_5}	2.91	3.00	3.09		
		V_{det1_6}	2.81	2.90	2.99		
		V_{det1_7}	2.70	2.79	2.88		
		V_{det1_8}	2.60	2.68	2.76		
		V_{det1_9}	2.50	2.58	2.66		
		V_{det1_A}	2.40	2.48	2.56		
		V_{det1_B}	1.99	2.06	2.13		
		V_{det1_C}	1.90	1.96	2.02		
		V_{det1_D}	1.80	1.86	1.92		

Note: • These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD2), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet1_n denotes the value of the LVDLVLR.LVD1LVL[3:0] bits.

Table 5.46 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Voltage detection circuit (LVD2)*1	V_{det2_0}	2.71	2.90	3.09	V	Figure 5.61 At falling edge VCC
		V_{det2_1}	2.43	2.60	2.77		
		V_{det2_2}	1.87	2.00	2.13		
		V_{det2_3}*2	1.69	1.80	1.91		
Wait time after power-on reset cancellation	At normal startup*3	t_{POR}	—	9.1	—	ms	Figure 5.59
	During fast startup time*4	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 1 reset cancellation	Power-on voltage monitoring 1 reset disabled*3	t_{LVD1}	—	568	—	µs	Figure 5.60
	Power-on voltage monitoring 1 reset enabled*4		—	100	—		
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.61
Response delay time		t_{det}	—	—	350	µs	Figure 5.58
Minimum VCC down time*5		t_{VOFF}	350	—	—	µs	Figure 5.58, VCC = 1.0 V or above
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.59, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	300	µs	Figure 5.60, Figure 5.61
Hysteresis width (LVD1 and LVD2)		V_{LVH}	—	70	—	mV	Vdet1_4 selected
			—	60	—		Vdet1_5 to 9, LVD2 selected
			—	50	—		When selection is from among Vdet1_A to B.
			—	40	—		When selection is from among Vdet1_C to D.

Note: • These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet2_n denotes the value of the LVDLVLR.LVD2LVL[3:0] bits.

Note 2. Vdet2_3 selection can be used only when the CMPA2 pin input voltage is selected and cannot be used when the power supply voltage (VCC) is selected.

Note 3. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.

Note 4. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.

Note 5. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

Table 5.50 ROM (Flash Memory for Code Storage) Characteristics (3)

Middle-speed operating mode Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	143	1330	—	96.8	932	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.3	269	—	5.85	219	ms
	256-Kbyte	t_{E256K}	—	407	928	—	93	520	ms
Blank check time	4-byte	t_{BC4}	—	—	78	—	—	50	µs
	1-Kbyte	t_{BC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t_{SED}	—	—	33.6	—	—	25.6	µs
Start-up area switching setting time		t_{SAS}	—	13.2	549	—	7.6	445	ms
Access window time		t_{AWS}	—	13.2	549	—	7.6	445	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	3	—	—	3	—	—	µs

Note: • Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: • The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: • The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

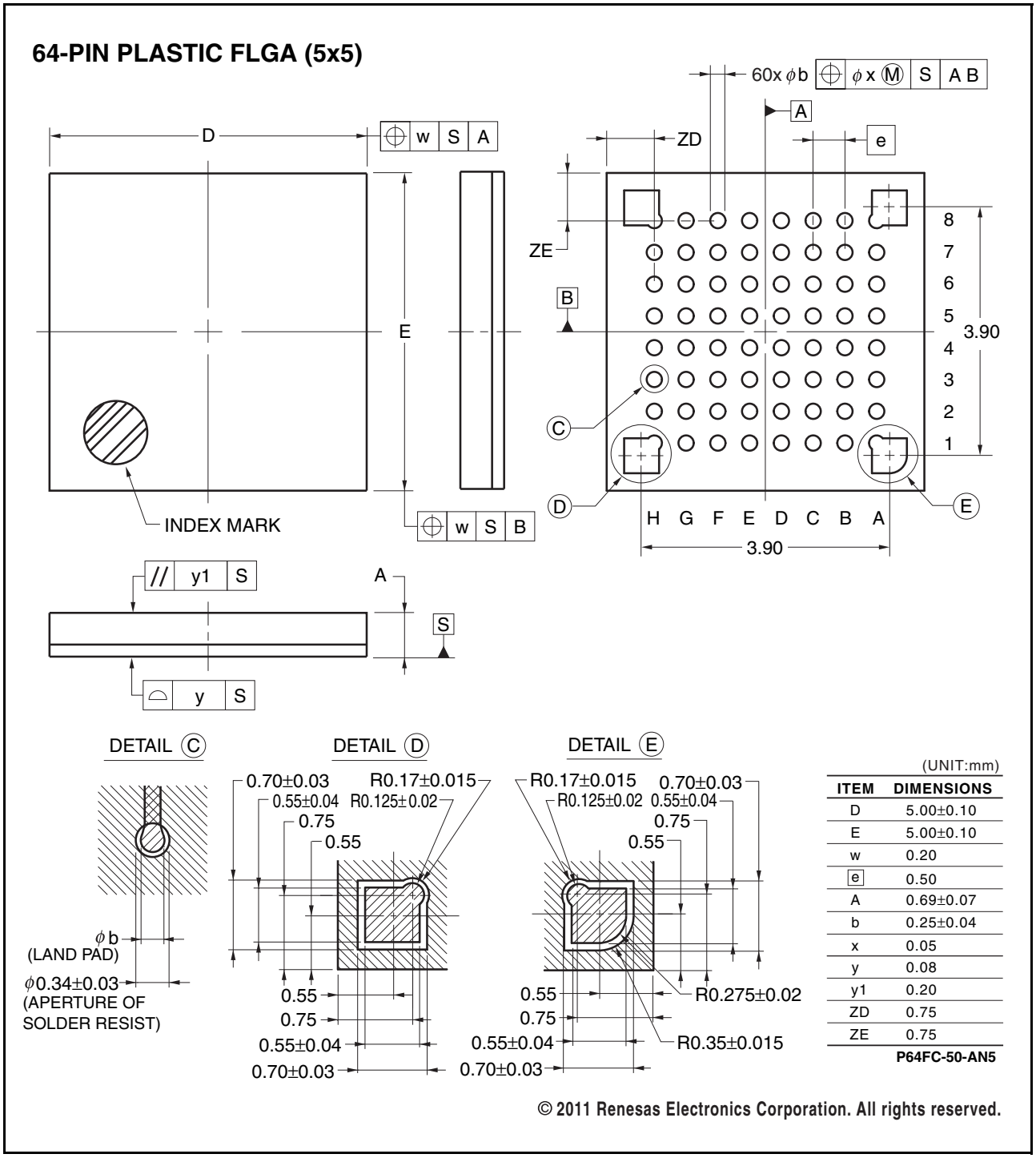
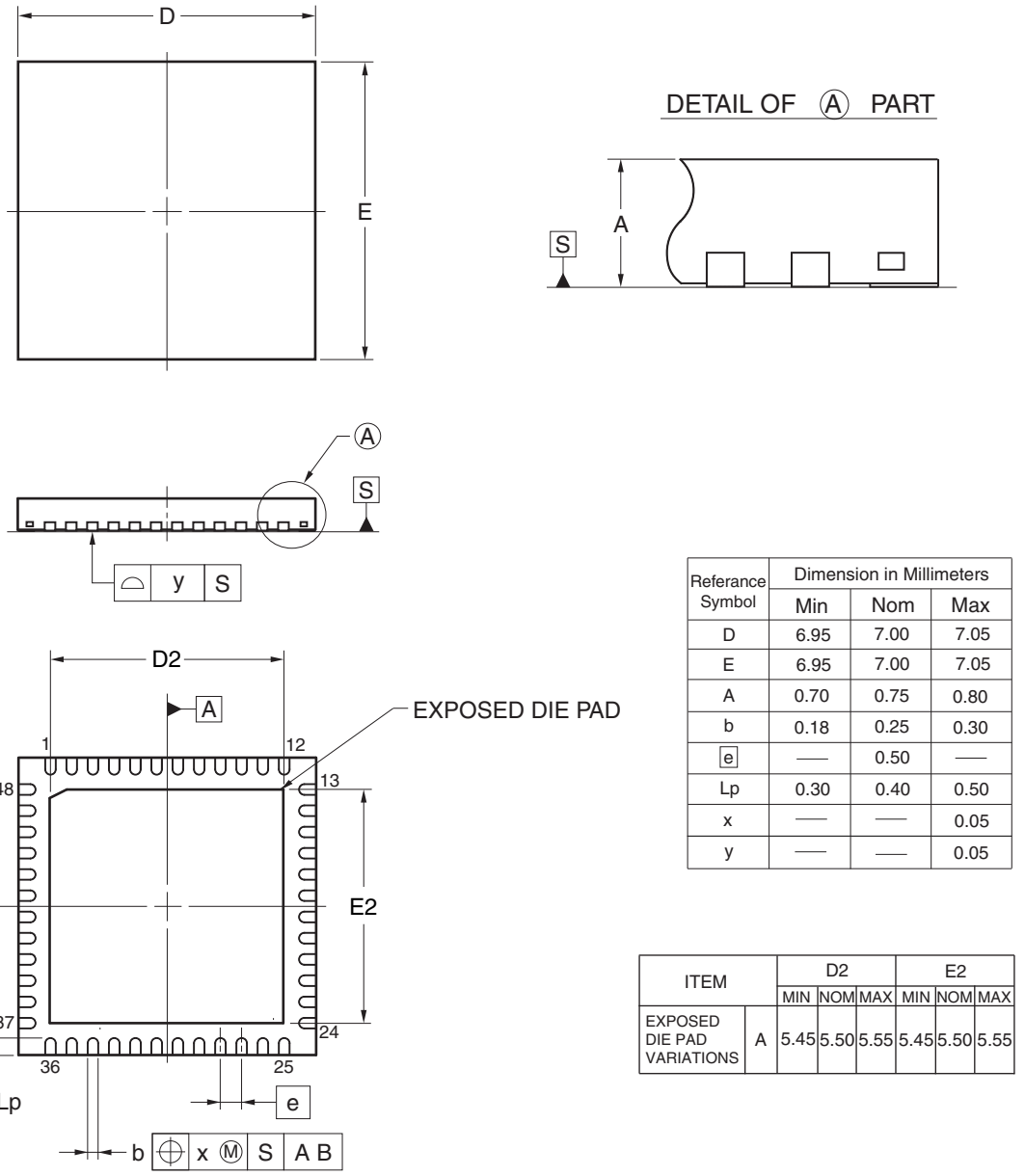


Figure C 64-Pin WFLGA (PWLG0064KA-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-5	0.13



Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.95	7.00	7.05
E	6.95	7.00	7.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05

ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	5.45	5.50	5.55	5.45	5.50	5.55

Figure E 48-Pin HWQFN (PWQN0048KB-A)

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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